



DUAL P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{D1D2}	R _{D1D2(ON)} Typ	I _{D1D2} T _A = +25°C
-20V	$63m\Omega @V_{GS} = -4.5V$	-3.1A

Description

This new generation MOSFET is designed to minimize the on-state resistance (R_{D1D2(ON)}) yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

Applications

- Battery management
- Load switches
- Battery protections



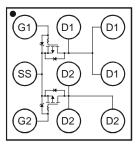
Features and Benefits

- LD-MOS Technology with the Lowest Figure of Merit:
 - R_{D1D2(ON)} = 63mΩ to Minimize On-State Losses
 - Q_q = 3.2nC for Ultra-Fast Switching
- V_{GS(TH)} = -0.74V typ for a Low Turn-On Potential
- CSP with Footprint 1.5mm x 1.5mm
- Height = 0.32mm for Low Profile
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative.

https://www.diodes.com/quality/product-definitions/

Mechanical Data

- Package: X2-DSN1515-9
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal: Finish SnAg over Cu Pillar (1)
- Solder Cap Material: SnAg (Ag: 2.0+/-0.5%)
- Terminal Connections: See Diagram Below
- Weight: 0.0015 grams (Approximate)



Top View

Ordering Information (Note 4)

Part Number	Package	Packing			
Fait Number	rackaye	Qty.	Carrier		
DMP2101UCP9-7	X2-DSN1515-9 (Type B)	3000	Tape & Reel		

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



6M = Product Type Marking Code YW = Date Code Marking Y or <u>Y</u> = Year (ex: 3 = 2023)

W or \overline{W} = Week (ex: a = week 27; z represents week 52 and 53)

Date Code Key

Date Code Rey												
Year	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032	2033
Code	2	3	4	5	6	7	8	9	0	1	2	3
Week	Week 1-26				27-52				53			
Code	A-Z			A-Z a-z							Z	



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Drain-to-Drain Voltage		V _{D1D2}	-20	V	
Gate-to-Source Voltage	V_{GS}	-6	V		
Continuous Drain Current (Note 5) Vgs = -4.5V	Steady State	T _A = +25°C T _A = +70°C	I _{D1D2}	-2.5 -2.0	А
Continuous Drain Current (Note 6) $V_{GS} = -4.5V$ Steady $T_A = +25^{\circ}C$ State $T_A = +70^{\circ}C$			I _{D1D2}	-3.1 -2.5	А
Continuous Source Pin Current (Note 6)		Is	-1.65	А	
Pulsed Source Pin Current (Pulse Duration 10µs, I	Outy Cycle	Ism	-22	Α	
Pulsed Drain Current (Pulse Duration 10µs, Duty C	ycle ≤ 1%	I _{DM}	-22	A	

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	PD	0.97	W
Total Power Dissipation (Note 6)	PD	1.47	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	130.3	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	RθJA	84.8	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

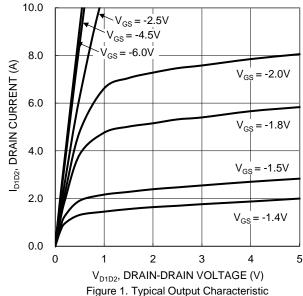
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)	, -			ı	I		
Drain-to-Drain Breakdown Voltage	BV _{D1D2}	-20	_	_	V	$V_{GS} = 0V$, $I_{D1D2} = -250\mu A$	
Zero Gate Voltage Drain Current @Tc = +25°C	IDDS	_	_	-1	μΑ	V _{D1D2} = -16V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	_	_	-100	nA	$V_{GS} = -6V$, $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)			•		•		
Gate Threshold Voltage	Vgs(th)	-0.4	-0.74	-0.9	V	$V_{D1D2} = V_{GS}, I_{DS} = -250 \mu A$	
		_	63	100		Vgs = -4.5V, I _{D1D2} = -1A	
Static Drain-to-Drain On-Resistance	R _{D1D2(ON)}	_	72	130	mΩ	$V_{GS} = -2.5V$, $I_{D1D2} = -1A$	
		_	87	175		Vgs = -1.8V, I _{D1D2} = -1A	
Diode Forward Voltage (Note 6)	VsD	_	-0.7	-1	V	Vgs = 0V, I _{D1D2} = -1A	
DYNAMIC CHARACTERISTICS (Note 8)						•	
Input Capacitance	C _{iss}	_	392	_	pF	101/1/	
Output Capacitance	Coss	_	183	_	pF	$V_{D1D2} = -10V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	Crss	_	8.4	_	pF	1 = 1.0ivii iz	
Total Gate Charge	Qg	_	3.2	_	nC		
Gate-Source Charge	Qgs	_	0.3	_	nC	$V_{GS} = -4.5V, V_{D1D2} = -10V,$	
Gate-Drain Charge	Qgd	_	0.6	_	nC	I _{D1D2} = -1A	
Gate Charge at Vth	Qg(th)	_	0.18	_	nC		
Turn-On Delay Time	t _{D(ON)}	_	3.6	_	ns		
Turn-On Rise Time	t _R	_	5.3	_	ns	V _{D1D2} = -10V, V _{GS} = -4.5V,	
Turn-Off Delay Time	t _D (OFF)	_	40	_	ns	$I_{D1D2} = -1A, R_G = 30\Omega$	
Turn-Off Fall Time	tF	_	20	_	ns	1	

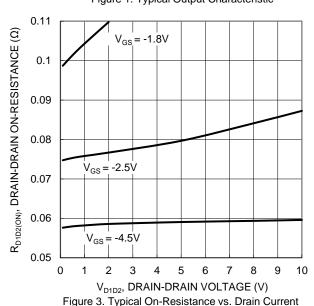
Notes:

- 5. Device mounted on FR-4 PCB with minimum recommended pad layout.
- 6. Device mounted on FR-4 material with 1inch² (6.45cm²), 2oz (0.071mm thick) Cu.
- 7. Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to production testing.

DMP2101UCP9







and Gate Voltage

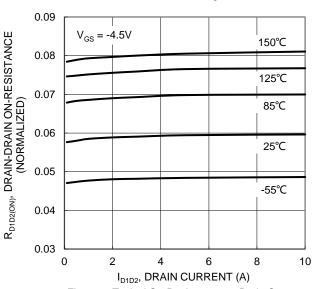
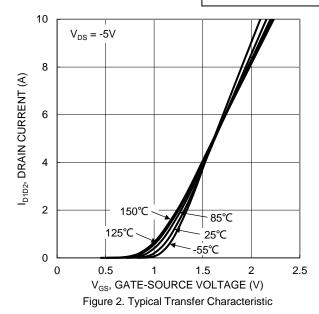
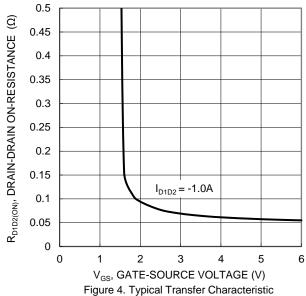


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature





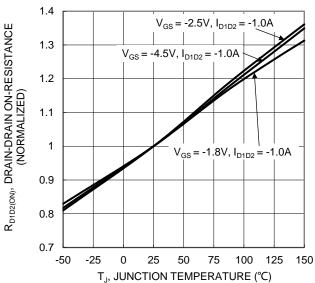


Figure 6. On-Resistance Variation with Junction Temperature

DMP2101UCP9

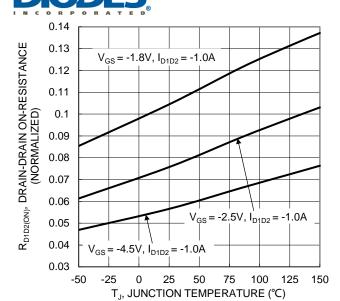
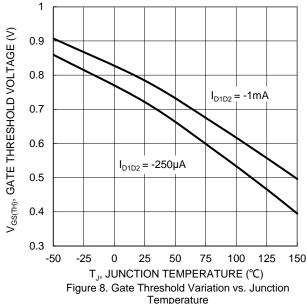


Figure 7. On-Resistance Variation with Junction Temperature



Temperature

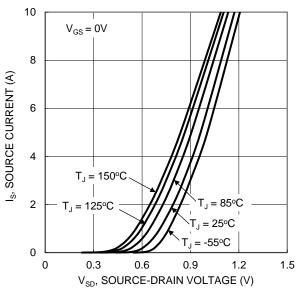
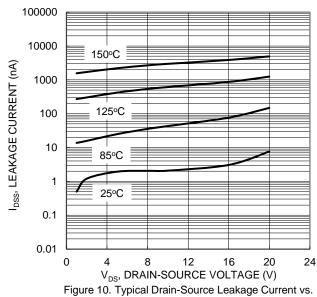
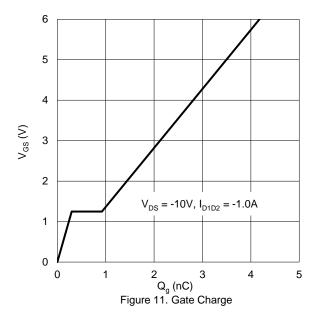


Figure 9. Diode Forward Voltage vs. Current



Voltage



100 R_{DS(ON)} Limited $P_{W} = 100 \mu s$ 10 ID, DRAIN CURRENT (A) $P_W = 10ms$ $P_W = 100 ms$ $T_{J(Max)} = 150^{\circ}C$ $T_A = 25^{\circ}C$ Single Pulse $P_W = 10s$ DUT on 1*MRP Board $V_{GS} = 4.5V$ 0.01 0.1 10 100 V_{DS}, DRAIN-SOURCE VOLTAGE (V) Figure 12. SOA, Safe Operation Area



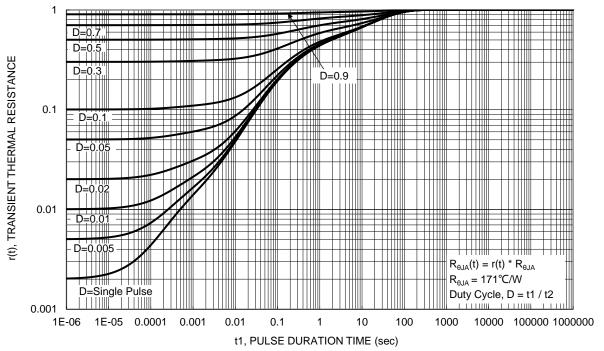


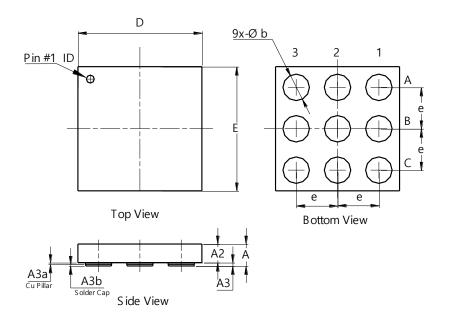
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DSN1515-9 (Type B)

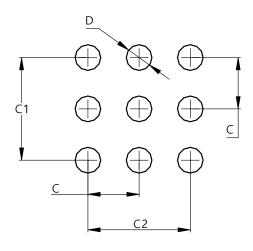


X2-DSN1515-9 (Type B)							
Dim	Min						
Α		0.32	0.265				
A2			0.225				
A3	0.034	0.046	0.040				
A3a	0.015	0.025	0.020				
A3b	0.017 0.023 0.02						
p	0.27 0.37 0.32						
D	1.45	1.53	1.50				
Е	1.45	1.53	1.50				
е	0.50						
Co- planarit y	<u><</u> 0.005						
All D	All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DSN1515-9 (Type B)



Dimensions	Value
Dilliensions	(in mm)
С	0.50
C1	1.00
C2	1.00
D	0.25



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